

SURFACE MOUNT ULTRA FAST RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Ultra fast switching for high efficiency
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed
250 °C/10 seconds at terminals

Mechanical Data

Case : JEDEC DO-214AA/SMB Molded plastic body

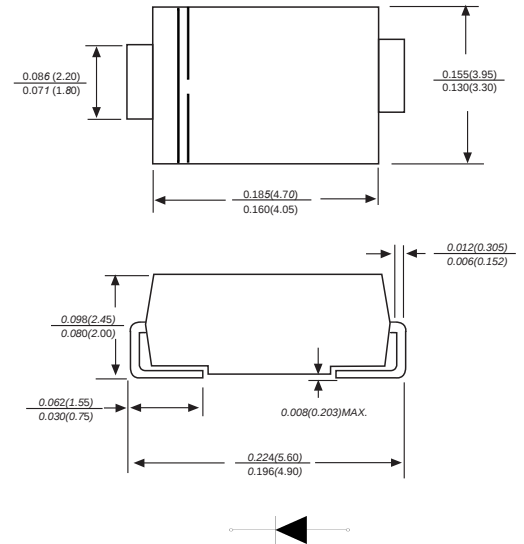
Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.003 ounce, 0.095 grams

DO-214AA/SMB



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

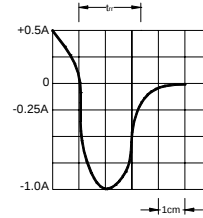
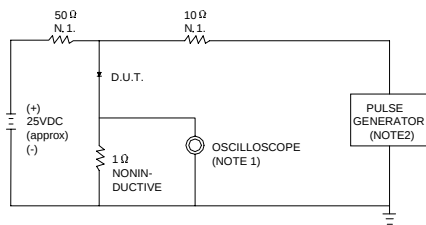
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MDD US5AB	MDD US5BB	MDD US5DB	MDD US5GB	MDD US5JB	MDD US5KB	MDD US5MB	UNITS
Marking Code									
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at TL=55 C	I _(AV)	5.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	I _{FSM}	100							A
Maximum instantaneous forward voltage at 5.0A	V _F	1.0			1.40	1.7			V
Maximum DC reverse current TA=25°C at rated DCblocking voltage TA=125°C	I _R	5.0 300.0							μA
Maximum reverse recovery time (NOTE 1)	t _{rr}	50				75			ns
Typical junction capacitance (NOTE 2)	C _J	15.0				12.0			pF
Typical thermal resistance (NOTE 3)	RθJA	15.0							°C/W
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +150							°C

Note: 1. Reverse recovery condition $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $t_{rr}=0.25\text{A}$
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 3. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

Ratings And Characteristic Curves

FIG.1 -- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC



NOTES:1.RISE TIME = 7ns MAX.INPUT IMPEDANCE = 1MΩ.22pF.
2.RISE TIME =10ns MAX.SOURCE IMPEDANCE=50 Ω.

SET TIME BASE FOR 20/30 ns/cm

FIG.2 -- TYPICAL FORWARD CHARACTERISTIC

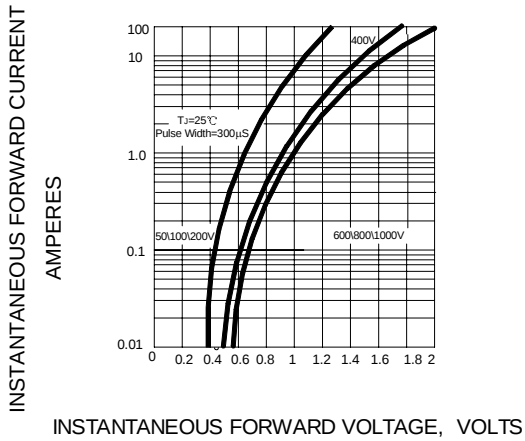


FIG.3 -- FORWARD DERATING CURVE

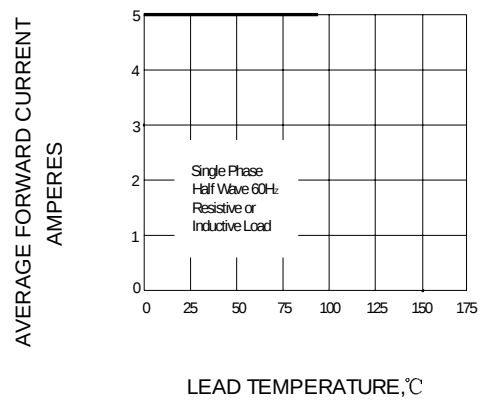


FIG.4 -- TYPICAL JUNCTION CAPACITANCE

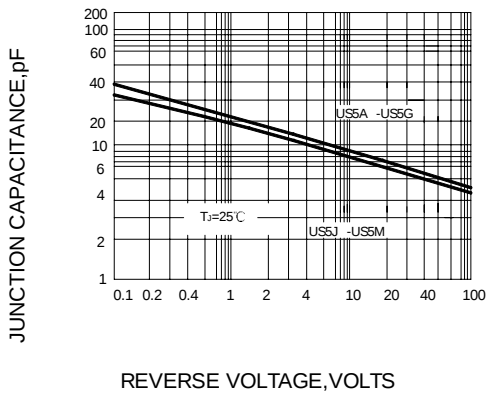
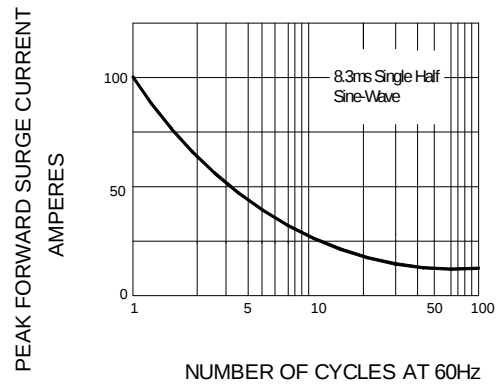
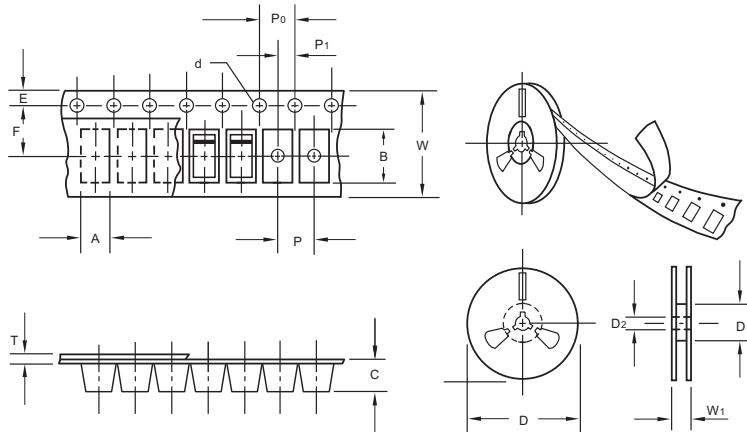


FIG.5 -- PEAK FORWARD SURGE CURRENT



The curve above is for reference only.

Packing information



unit:mm

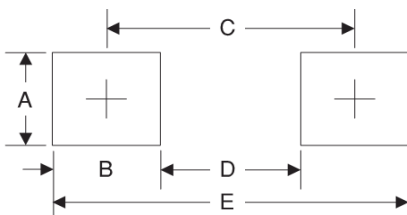
Item	Symbol	Tolerance	SMB
Carrier width	A	0.1	3.81
Carrier length	B	0.1	5.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1 5.0
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.55
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W ₁	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMB	13"	3,000	4.0	6,000	190*190*41	330	365*365*360	48,000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	2.8	0.110
B	2.4	0.094
C	4.6	0.181
D	2.2	0.086
E	7.0	0.276